

SOT2075-1

TFBGA56, thin fine-pitch ball grid array package, 56 terminals,
0.4 mm pitch, 4 mm x 4 mm x 1.1 mm body

28 April 2022

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	TFBGA56
Package style descriptive code	TFBGA (thin fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	18-10-2021
Manufacturer package code	98ASA01663D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	4	-	
package width	-	4	-	mm
seated height	-	1.1	1.2	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	56	-	



TFBGA56, thin fine-pitch ball grid array package, 56 terminals, 0.4 mm pitch, 4 mm x 4 mm x 1.1 mm body

2 Package outline

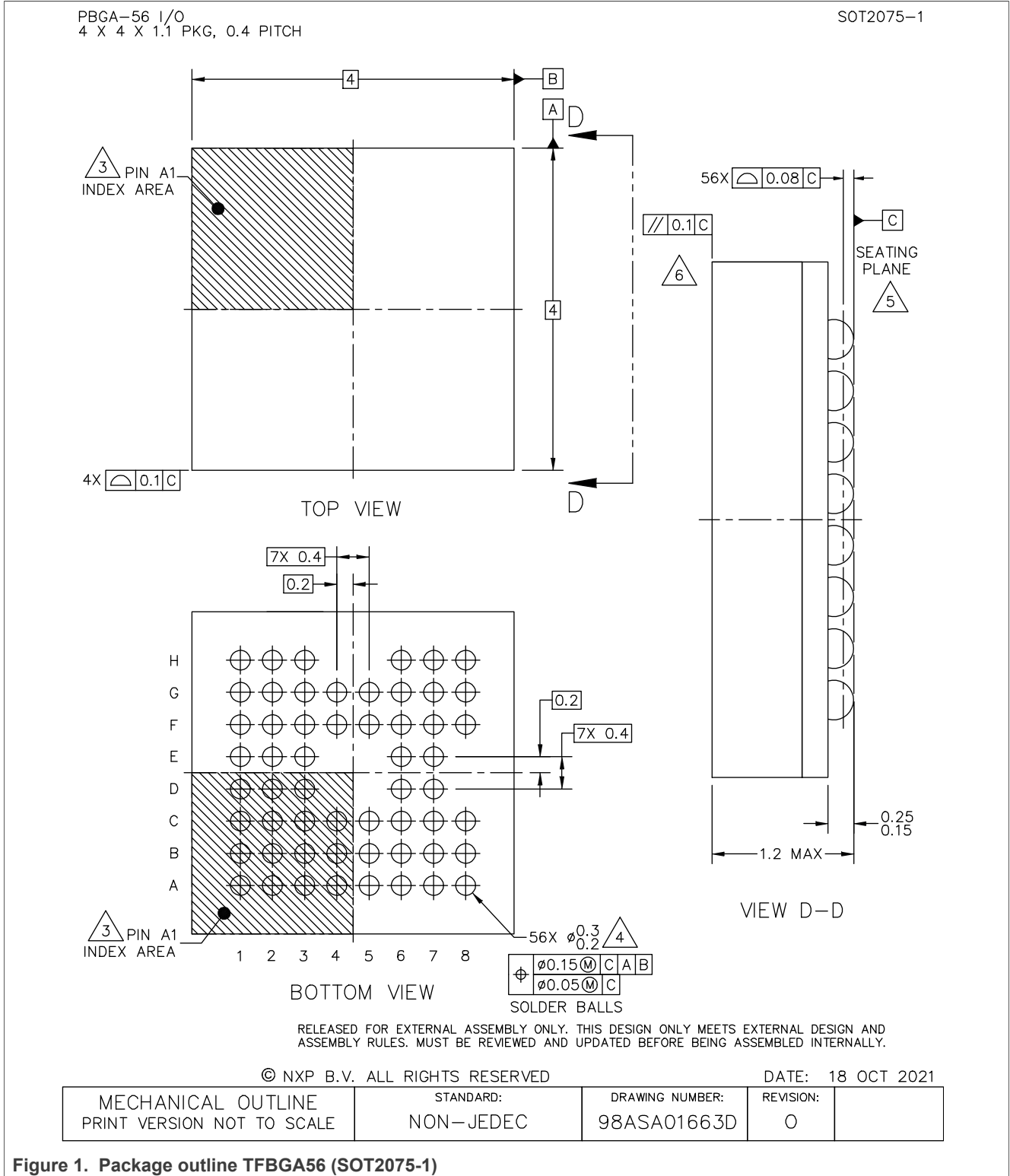


Figure 1. Package outline TFBGA56 (SOT2075-1)

3 Soldering

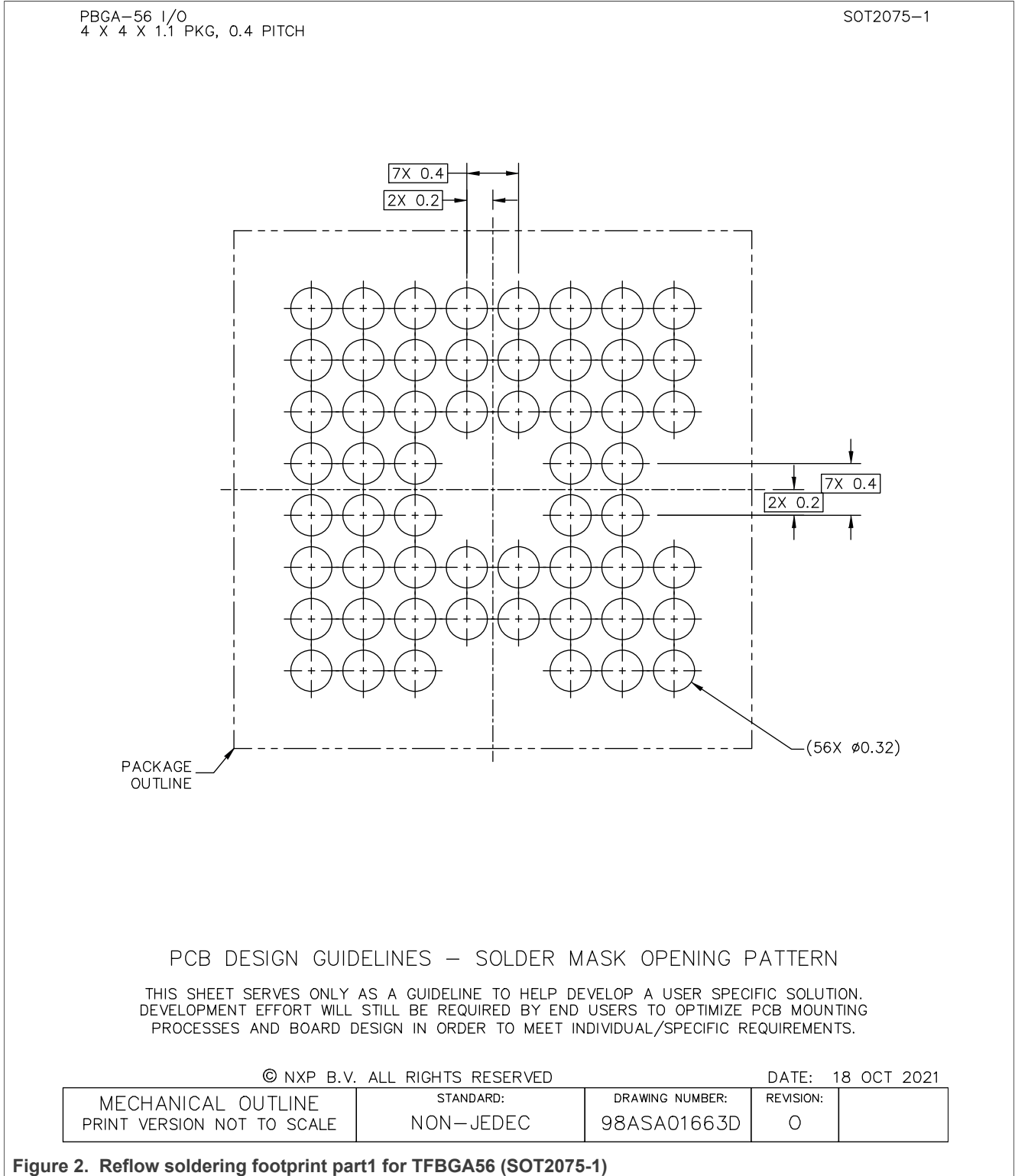
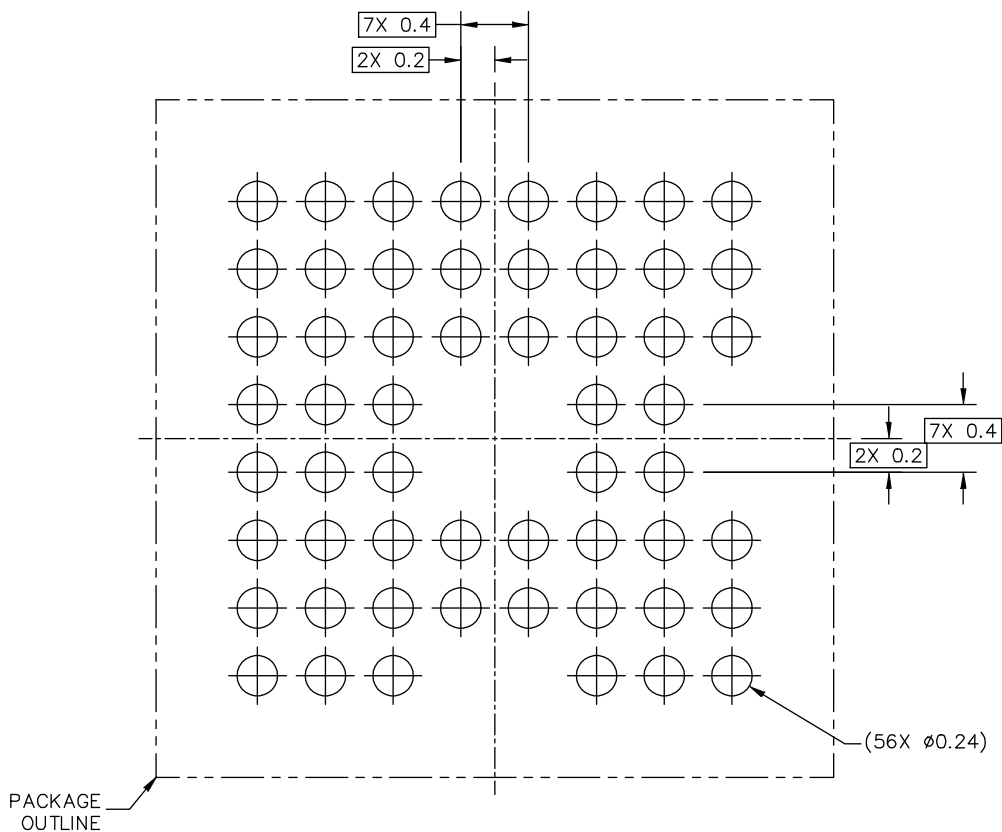


Figure 2. Reflow soldering footprint part1 for TFBGA56 (SOT2075-1)

TFBGA56, thin fine-pitch ball grid array package, 56 terminals, 0.4 mm pitch, 4 mm x 4 mm x 1.1 mm body

PBGA-56 I/O
4 X 4 X 1.1 PKG, 0.4 PITCH

SOT2075-1



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

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DATE: 18 OCT 2021

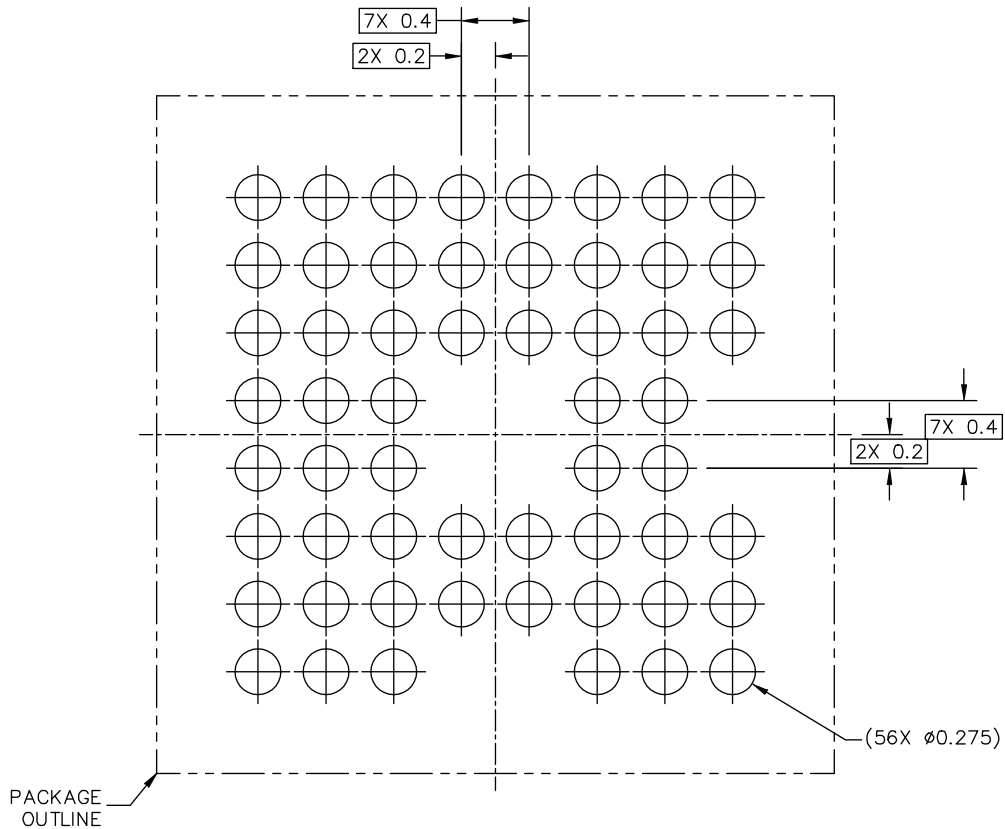
MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA01663D	REVISION: 0	
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Figure 3. Reflow soldering footprint part2 for TFBGA56 (SOT2075-1)

TFBGA56, thin fine-pitch ball grid array package, 56 terminals, 0.4 mm pitch, 4 mm x 4 mm x 1.1 mm body

PBGA-56 I/O
4 X 4 X 1.1 PKG, 0.4 PITCH

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RECOMMENDED STENCIL THICKNESS 0.1

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Figure 4. Reflow soldering footprint part3 for TFBGA56 (SOT2075-1)

TFBGA56, thin fine-pitch ball grid array package, 56 terminals, 0.4 mm pitch, 4 mm x 4 mm x 1.1 mm body

PBGA-56 I/O
4 X 4 X 1.1 PKG, 0.4 PITCH

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NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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Figure 5. Package outline note TFBGA56 (SOT2075-1)

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TFBGA56, thin fine-pitch ball grid array package, 56 terminals, 0.4 mm pitch, 4 mm x 4 mm x 1.1 mm
body

Contents

1	Package summary	1
2	Package outline	2
3	Soldering	3
4	Legal information	7